



Material Content Data Sheet



Sales Product Name		IPD60R180P7S		Issued		1. August 2018		
MA#		MA001983732						
Package		PG-TO252-3-343		Weight*		313.01 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.174	1.33	1.33	13336	13336
leadframe	inorganic material	phosphorus	7723-14-0	0.041	0.01		132	
	non noble metal	iron	7439-89-6	0.137	0.04		439	
	non noble metal	copper	7440-50-8	137.105	43.82	43.87	438018	438589
	non noble metal	aluminium	7429-90-5	0.436	0.14	0.14	1392	1392
wire	non noble metal	aluminium	7429-90-5	0.436	0.14	0.14	1392	1392
encapsulation	organic material	carbon black	1333-86-4	1.307	0.42		4176	
	plastics	epoxy resin	-	24.835	7.93		79343	
	inorganic material	silicondioxide	60676-86-0	104.569	33.41	41.76	334074	417593
leadfinish	non noble metal	tin	7440-31-5	3.834	1.22	1.22	12247	12247
solder	non noble metal	tin	7440-31-5	0.071	0.02		226	
	noble metal	silver	7440-22-4	0.088	0.03		282	
	non noble metal	lead	7439-92-1	3.376	1.08	1.13	10787	11295
heatspreader	inorganic material	phosphorus	7723-14-0	0.010	0.00		32	
	non noble metal	iron	7439-89-6	0.033	0.01		106	
	non noble metal	copper	7440-50-8	32.995	10.54	10.55	105410	105548
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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